# Winstar Display Co., LTD 華凌光電股份有限公司



住址: **407** 台中市中清路 **163** 號 No.163 Chung Ching RD., Taichune, Taiwan, R.O.C

**CUSTOMER** 

WEB: <a href="http://www.winstar.com.tw">http://www.winstar.com.tw</a>
E-mail: sales@winstar.com.tw
Tel:886-4-24262208 Fax: 886-4-24262207

## **SPECIFICATION**

MODULE NO.:	WG12864D-TMI-NZ#000				
APPROVED BY:  ( FOR CUSTOMER USE ONLY )	PCB VERSION:	DATA:			

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/3/9		First issue



RECO	ORDS OF REV	/ISION	DOC. FIRST ISSUE
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## 1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type

 $\odot$  Display Font : 128 x , 64 dots

Model serials no.

 $\bigcirc$  Backlight Type: N $\rightarrow$ Without backlight A $\rightarrow$ LED, Amber

 $B\rightarrow EL$ , Blue green  $R\rightarrow LED$ , Red  $D\rightarrow EL$ , Green  $O\rightarrow LED$ , Orange  $W\rightarrow EL$ , White  $G\rightarrow LED$ , Green

 $F \rightarrow CCFL$ , White  $T \rightarrow LED$ , White

Y→LED, Yellow Green

© LCD Mode :  $B \rightarrow TN$  Positive, Gray  $T \rightarrow FSTN$  Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00

range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00

direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code
N: Without Negative Voltage; Z:NT7086 driver IC

00: Sales code 0:version(TS12864CRNA#)

#:Fit in with the ROHS Directions and regulations

## 2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8). Winstar have the right to change the passive components
- (9). Winstar have the right to change the PCB Rev.

## 3.General Specification

Item	Dimension					
Number of Characters	128 x 64	_				
Module dimension	78.0 x 70.0 x 15.4(MAX)	mm				
View area	62.0 x 44.0	mm				
Active area	56.3 x 38.38	mm				
Dot size	0.42 x 0.58	mm				
Dot pitch	0.44 x 0.60	mm				
LCD type	STN, Negative, Blue, Transmissive  (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)					
Duty	1/64					
View direction	6 o'clock					
Backlight Type	LED, White					

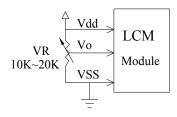
## 4. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{OP}$	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V <sub>I</sub>	Vss	_	$V_{ m DD}$	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3	_	+7	V
Supply Voltage For LCD	$V_{ m DD} ext{-}V_0$	0	_	15	V
Negative Voltage Output	$V_{ ext{EE}}$	_	10	_	V

## 5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$ m V_{DD} ext{-}V_{SS}$	_	4.75	5.0	5.25	V
Supply Voltage For LCD		Ta=-20°C	_	_	9.8	V
*Note	$ m V_{DD} ext{-}V_0$	Ta=25°C	_	8.5	_	V
		Ta=70°C	7.6	_	_	V
Input High Volt.	$V_{ m IH}$	_	V <sub>DD</sub> -2.2	_	$V_{ m DD}$	V
Input Low Volt.	$V_{\rm IL}$	_	0	_	0.8	V
Output High Volt.	$V_{\mathrm{OH}}$	_	V <sub>DD</sub> -0.3	_	$V_{ m DD}$	V
Output Low Volt.	$V_{\mathrm{OL}}$	_	0	_	0.3	V
Supply Current	$I_{DD}$	V <sub>DD</sub> =5V	8.0	10.5	12.	mA

<sup>\*</sup> Note: Please design the VOP adjustment circuit on customer's main board

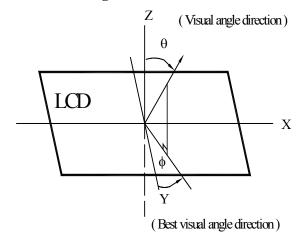


## 6. Optical Characteristics

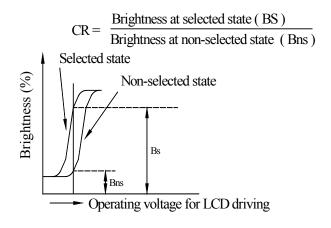
ITEM	SYMBAL	CONDITION	MIN.	TYP.	MAX.	UNIT
	(V) θ	CR≧2	20	_	40	deg
View Angle	(H) φ	CR≧2	-30	_	30	deg
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	200	300	ms

## **6.1 Definitions**

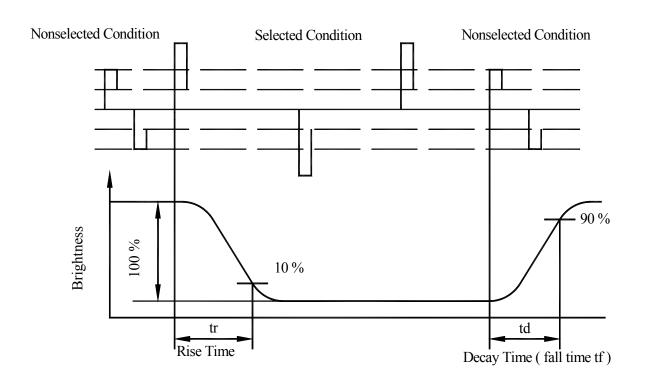
## **■View Angles**



### **Contrast Ratio**



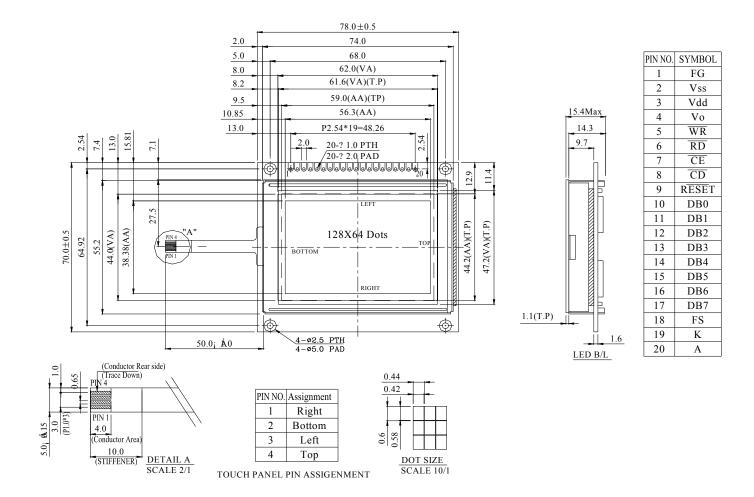
## **Response Time**

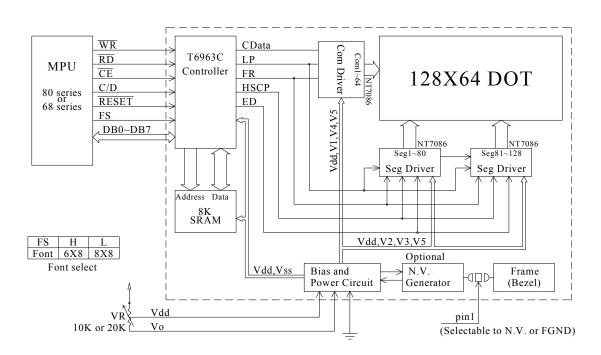


# 7. Interface Pin Function

Pin No.	Symbol	Level	Description
1	FG		Frame Ground
2	Vss		GND
3	Vdd		Power supply ( +5 V )
4	Vo		Power supply for LCD driver
5	WR	L	Data write. Write data into T6963C when WR = L
6	RD	L	Data read. Read data from T6963C when RD = L
7	CE	L	L : Chip enable
8	C/D	H/L	WR=L, C/D=H: Command Write C/D=L: Data write
			RD=L, C/D=H: Status Read C/D=L: Data read
9	RESET	H/L	H: Normal; L: Initialize T6963C
10	DB0	H/L	Data bus line
11	DB1	H/L	Data bus line
12	DB2	H/L	Data bus line
13	DB3	H/L	Data bus line
14	DB4	H/L	Data bus line
15	DB5	H/L	Data bus line
16	DB6	H/L	Data bus line
17	DB7	H/L	Data bus line
18	FS	H/L	Pins for selection of font; H: 6 * 8, L: 8 * 8
19	K		Power supply for LED B/L -
20	A		Power supply for LED B/L +

## 8. Contour Drawing & Block Diagram





External contrast adjustment.

## 9. Display control instruction

The LCD Module has built in a T6963C LSI controller, It has an 8-bit parallel data bus and control lines for writing or reading through an MPU interface, it has a 128-word character generator ROM (refer to Table 1.), which can control an external display RAM of up to 8K bytes. Allocation of text, graphics and external character generator RAM can be made easily and the display window can be moved freely within the allocated memory range.

#### •RAM Interface

The external RAM is used to store display data( text, graphic and external CG data ). It can be freely allocated to the memory area( 8 Kbyte max ).

#### Recommend

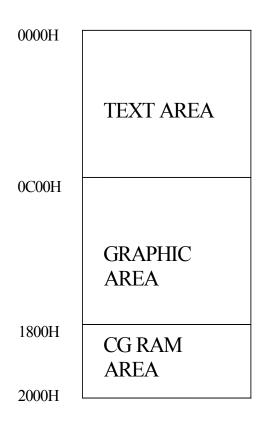


Table 1.

CHARACTER CODE MAP
ROM code 0101

LSB	_	4	_	_		_	_	7			_	_	_	_	-	_
MSB	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Е	F
0		•	••		#	<b></b>				•	#	+	:	<b></b>	<b>::</b>	. •
1		1	2	3	4	5	6	7	8	9	::	:	<	<b></b>	>	?
2		Ĥ								I		K	<b></b>	M	N	
3				5	Ï		Ņ	W	X	Y	Z		٠.		•	
4	•	₽		<b></b>			#	∰	h	i	j	K	1	m	ľì	
5	<b>:::</b>	-=	<b>!</b>	<b>≡</b> .	<b>-</b>	<b></b> !	Ų	W	×	₩	<b>=</b>	€.		}	***	
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#### • Flowchart of communications with MPU

### (1)Status Read

A status check must be performed before data is read or written.

### Status check

The Status of T6963C can be read from the data lines.

 $\begin{array}{cccc} \overline{RD} & & L \\ \overline{WR} & & H \\ \hline \overline{CE} & & L \\ C/D & & H \\ Do to D7 & & H \end{array}$ 

The T6963C status word format is as follows:

MSB LSB STA7 STA6 STA5 STA4 STA3 STA2 STA1 STA0 **D**7 D6 D5 D4 D3D2D1 D0

STA0	Check command execution capability	0:Disable 1:Enable
STA1	Check data read/write Capability	0:Disable 1:Enable
STA2	Check Auto mode data read capability	0:Disable 1:Enable
STA3	Check Auto mode data write capability	0:Disable 1:Enable
STA4	Not used	
STA5	Check controller operation capability	0:Disable 1:Enable
STA6	Error flag. Used for Screen Peek and Screen copy commands.	0:No error 1:Error
STA7	Check the blink condition	0:Disable off 1:Normal display

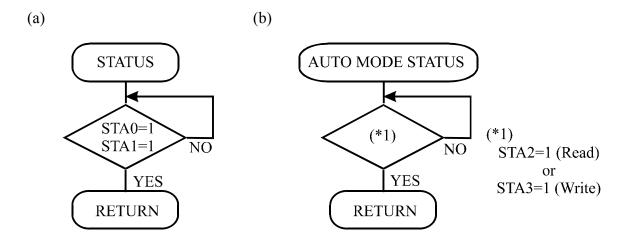
(Note 1) It is necessary to check STA0 and STA1 at the same time.

There is a possibility of erroneous operation due to a hardware interrupt.

(Note 2) For most modes STA0/STA1 are used as a status check.

(Note 3) STA2 and STA3 are valid in Auto mode; STA0 and STA1 are invalid.

Status Checking flow



(Note 4) When using the MSB=0 command, a Status Read must be performed.

If a status check is not carried out, the T6963C cannot operate normally, even after a delay time.

The hardware interrupt occurs during the address calculation period (at the end of each line).

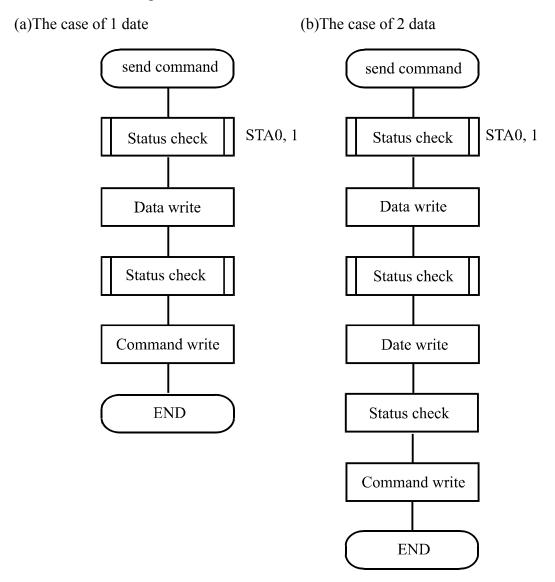
If a MSB=0 command is sent to the T6963C during this period, the T6963C enters Wait status.

If a status check is not carried out in this state before the next command is sent, there is the possibility that the command or data date will not be received.

## (2)Setting date

When using the T6963C, first set the data, then set the command.

### Procedure for sending a command



(Note) When sending more than two data, the last datum (or last two data)is valid.

### • COMMAND DEFINITIONS

COMMAND	CODE	D1	D2	FUNCTION
	00100001	X address	Y address	Set Cursor Pointer
REGISTERS SETTING	00100010	Date	00H	Set Offset Register
	00100100	Low address	High address	Set Address Pointer
	01000000	Low address	High address	Set Text Home Address
SET CONTROL WORD	01000001	Columns	00H	Set Text Area
SET CONTROL WORD	01000010	Low address	High address	Set Graphic Home Address
	01000011	Columns	00H	Set Graphic Area
	1000×000	_	_	OR mode
	1000×001	_	_	EXOR mode
MODE CET	1000×011	_	_	AND mode
MODE SET	1000×100	_	_	Text Attribute mode
	10000xxx	_	_	Internal CG ROM mode
	10001xxx	_	_	External CG RAM mode
	10010000	_	_	Display off
DISPLAY MODE	1001xx10	_	_	Cursor on, blink off
	10001xx11	_	_	Cursor on, blink on
	100101xx	_	_	Text on, graphic off
	100110xx	_	_	Text off, graphic on
	100111××	_	_	Text on, graphic on
	10100000	_	_	1-line cursor
	10100001	_	_	2-line cursor
	10100010	_	_	3-line cursor
CURSOR PATTERN	10100011	_	_	4-line cursor
SELECT	10100100			5-line cursor
	10100101	_	_	6-line cursor
	10100110	_	_	7-line cursor
	10100111	_	_	8-line cursor
DATA AUTO	10110000	_	_	Set Data Auto Write
READ/WRITE	10110001	_	_	Set Data Auto Read
KLAD/WKIIE	10110010	_	_	Auto Reset
	11000000	Data	_	Data Write and Increment ADP
DATA READ/WRITE	11000001	_	_	Data Read and Increment ADP
	11000010	Data	_	Data Write and Decrement ADP
DAIA KEAD/WKIIE	11000011	_	_	Data Read and Decrement ADP Data
	11000100	Data	_	Write and Nonvariable ADP
	11000101	_	_	Data Read and Nonvariable ADP
SCREEN PEEK	11100000	_	_	Screen Peek

X : invalid

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COMMAND	CODE	D1	D2	FUNCTION
SCREEN COPY	11101000			Screen Copy
	11110xxx	_	_	Bit Reset
	111111xxx	_	_	Bit Set
	1111×000	_	_	Bit 0 (LSB)
	11111×001	_	_	Bit 1
	11111×010	_	_	Bit 2
BIT SET/RESET	11111×011	_	_	Bit 3
	11111×100	_	_	Bit 4
	11111×101	_	_	Bit 5
	11111×110	_	_	Bit 6
	11111×111		_	Bit 7 (MSB)

X : invalid

#### Setting registers

	CODE	HEX.	FUNCTION	D1	D2
ı	00100001	21H	SET CURSOR POINTER	X ADRS	Y ADRS
	00100010	23H	SET OFFSET REGISTER	DATA	00H
	00100100	24H	SET ADDRESS POINTER	LOW ADRS	HIGH ADRS

#### (1)Set Cursor Pointer

The position of the cursor is specified by X ADRS and Y ADRS. The cursor position can only be moved by this command. Data read/write from the MPU never changes the cursor pointer. X ADRS and Y ADRS are specified as follows.

X ADRS 00H to 4FH (lower 7 bits are valid)

Y ADRS 00H to 1FH (lower 5 bits are valid)

Single-Scan

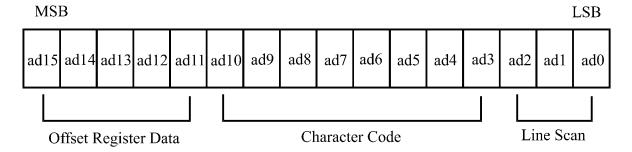
X ADRS 00 to 4FH

Y ADRS 00H to 0FH

### (2)Set Offset Register

The offset register is used to determine the external character generator RAM area.

The T6963C has a 16-bit address bus as follows.



T6963C assign External character generator, when character code set 80H TO FFH in using internal character generator. Character code 00H to 80H assign External character generator, when External generator mode.

The senior five bits define the start address in external memory of the CG RAM area. The next eight bits represent the character code of the character. In internal CG ROM, character codes 00H to 7FH represent the predefined "internal" CG ROM characters, and codes 80H to FFH represent the user's own "external" characters. In external CG ROM mode, all 256 codes from 00H to FFH can be used to represent the user's own characters. The three least significant bits

indicate one of the eight rows of eight dots that define the character's shape.

## The relationship between display RAM address and offset register

Offset register	data	CG RAM hex. address (start to end)
00000		0000 to 07 FFH
00001		0800 to 0FFFH
00010		1000 to 17FFH
11100		E000 to E7FFH
11101		E800 to EFFFH
11110		F000 to F7FFH
11111		F800 to FFFFH
(Example 1)		
Offset register		02H
Character code		80H
Character generat	or RAM start address	0001 0100 0000 0000
		1 4 0 0 H
		(address) (data)
		1400H 00H
		1401H 1FH
		1402H 04H
		1403H 04H
		0.411

(Example 2) The relationship between display RAM data and display characters

04H

04H

04H

00H

1404H

1405H

1406H

1407H

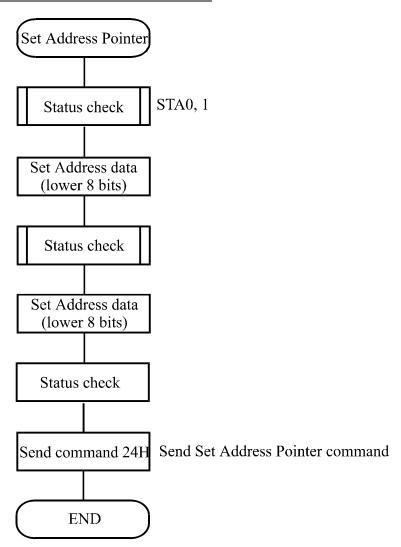
	(RAM DATA)	(Character)
AD ~ DE & CHIIKI M	21H	A
AB $\gamma$ DE $\zeta$ GHIJKLM .	22H	В
	83H	$\gamma$
:	24H	D
	25H	E
Display character	В6Н	ζ

 $\gamma$  and  $\zeta$  are displayed by character generator RAM.

### (3)Set Address Pointer

The Set Address Pointer command is used to indicate the start address for writing to (or reading from)external RAM.

### The Flowchart for Set Address Pointer command



#### · Set Control Word

CODE	HEX.	FUNCTION	D1	D2
01000000	40H	Set Text Home Address	Low address	High address
01000001	41H	Set Text Area	Columns	00H
01000010	42H	Set Graphic Home Address	Low address	High address
01000011	43H	Set Graphic Area	Columns	00H

The home address and column size are defined by this command.

### (1)Set Text Home Address

The starting address in the external display RAM for text display is defined by this command.

The text home address indicates the leftmost and uppermost position.

The relationship between external display RAM address and display position

TH	TH+CL
TH+TA	TH+TA+CL
(TH+TA)+TA	TH+2TA+CL
(TH+2TA)+TA	TH+3TA+CL
TH+(n-1)TA	TH+(n-1)TA+CL

TH:Text home address

TA:Text area number (columns)

CL:Columns are fixed by hardware (pin-programmable).

### (Example)

Text home address : 0000H
Text area : 0020H

: 32 Columns

: 4 Lines

0000Н	0001H	001EH	001FH
0020Н	0021H	003EH	002FH
0040H	0041H	005EH	005FH
0060Н	0061Н	007EH	007FH

### (2)Set Graphic Home Address

The starting address of the external display RAM used for graphic display is defined by this command. The graphic home address indicates the leftmost and uppermost position.

The relationship between external display RAM address and display position

GH	GH+GL
GH+GA	GH+GA+CL
(GH+GA)+GA	GH+2GA+CL
(GH+2GA)+GA	GH+3GA+CL
GH+(n-1)GA	GH+(n-1)GA+CL

GH:Graphic home address

GA:Graphic area number (columns)

CL:Columns are fixed by hardware (pin-programmable).

(Example)

Graphic home address : 0000H

Graphic area : 0020H

: 32 Columns

: 2 Lines

0000Н	0001H	001EH	001FH
0020H	0021H	003EH	003FH
0040H	0041H	005EH	005FH
0060Н	0061H	007EH	007FH
0080Н	0081H	009EH	009FH
00A0H	00A1H	00BEH	00BFH
00C0H	00C1H	00DEH	00DFH
00E0H	00E1H	00FEH	00FFH
0100H	0101H	011EH	011FH
0120H	0121H	013EH	013FH
0140H	0141H	015EH	014FH
0160H	0161H	017EH	017FH
0180H	0181H	109EH	019FH
01A0H	01A1H	01BEH	01BFH
01C0H	01C1H	01DEH	01DFH
01E0H	01E1H	01FEH	01FFH

## (3)Set Text Area

The display columns are defined by the hardware Setting. This command can be used to adjust the columns of the display.

## (Example)

LCD size 20 columns, 4lines

Text home address 0000H

Text area 0014H

Set 32 columns, 4 Lines

0000	0001	•••••	0013	0014	•••••	001F
0014	0015		0027	0028		0033
0028	0029	•••••	003B	003C	•••••	0047
003C	003D	•••••	004F	0050		005B



## (4)Set Graphic Area

The display columns are defined by the hardware setting. This command can be used to adjust the columns of the graphic display.

### (Example)

LCD size 20 columns, 2lines

Graphic home address : 0000H

Graphic are : 0014H

Set 32 columns, 2 Lines

0000	0001	•••••	0013	0014	•••••	001F
0014	0015	•••••	0027	0028	•••••	0033
0028	0029		003B	003C		0047
003C	003D		004F	0050		005B
0050	0051	•••••	0063	0064		006F
0064	0065	•••••	0077	0078	•••••	0083
0078	0079	•••••	008B	008C		0097
008C	008D	•••••	009F	00A0		00AB
00A0	00A1	•••••	00B3	00B4	•••••	00BF
00B4	00B5		00C7	00C8		00D3
00C8	00C9	•••••	00DB	00DC		00E7
00DC	00DD	•••••	00EF	00F0	•••••	00FD
00F0	00F1	•••••	0103	0104	•••••	011F
0104	0105		0127	0128		0123
0128	0129	•••••	013B	0013C	•••••	00147
013C	013D		014F	0150		015B



If the graphic area setting is set to match the desired number of columns on the LCD, the addressing scheme will be automatically modified so that the start address of each line equals the end address of the previous line +1.

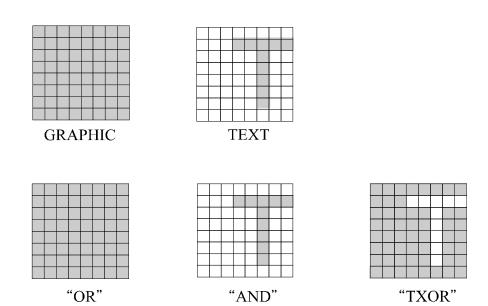
#### • Mode set

CODE	FUNCTION	OPERAND
1000×000	OR Mode	
1000×001	EXOR Mode	
1000×011	AND Mode	_
1000×100	TEXT ATTRIBUTE Mode	_
10000×××	Internal Character Generator Mode	_
10001xxx	External Character Generator Mode	_

X:invalid

The display mode is defined by this command. The display mode does not change until the next command is sent. The logical OR, EXOR, AND of text or graphic display can be displayed. In Internal Character Generator mode, character codes 00H to 7FH are assigned to the built-in character generator ROM. The character codes 80H to FFH are automatically assigned to the external character generator RAM.

### (Example)



(Note)Attribute functions can only be applied to text display, since the attribute data is placed in the graphic RAM area.

#### Attribute function

The attribute operations are Reverse display, Character blink and Inhibit. The attribute data is written into the graphic area which was defined by the Set Control Word command. Only text display is possible in Attribute Function mode; graphic display is automatically disabled. However, the Display Mode command must be used to turn both Text and Graphic on in order for the Attribute function to be available.

The attribute data for each character in the text area is written to the same address in the graphic

area. The Attribute function is defined as follows.

## Attribute RAM 1byte

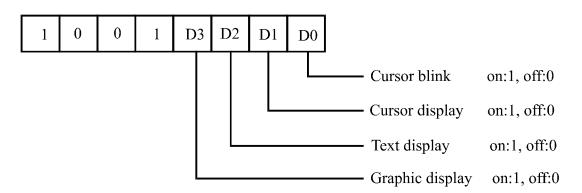
				•
d3	d2	d1	d0	FUNCTION
0	0	0	0	Normal display
0	1	0	1	Reverse display
0	0	1	1	Inhibit display
1	0	0	0	Blink of normal display
1	1	0	1	Blink of reverse display
1	0	1	1	Blink of inhibit display

X:invalid

### • Display mode

CODE	FUNCTION	OPERAND
10010000	Display off	
1001xx10	Cursor on, blink off	_
1001××11	Cursor on, blink on	_
100101××	Text on, graphic off	_
100110××	Text off, graphic on	_
100111××	Text on, graphic on	_

X:invalid



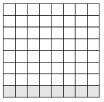
(Note)It is necessary to turn on "Text display" and "Graphic display" in the following cases.

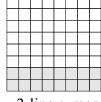
- a)Combination of text/graphic display
- b)Attribute function

#### Cursor pattern select

CODE	FUNCTION	OPERAND
10100000	1-line cursor	_
10100001	2-line cursor	_
10100010	3-line cursor	_
10100011	4-line cursor	_
10100100	5-line cursor	_
10100101	6-line cursor	
10100110	7-line cursor	
10100111	8-line cursor	_

When cursor display is ON, this command selects the cursor pattern in the range 1 line to 8 lines. The cursor address is defined by the Cursor Pointer Set command.







1-line cursor

2-line cursor

8-line cursor

#### · Data Auto Read/Write

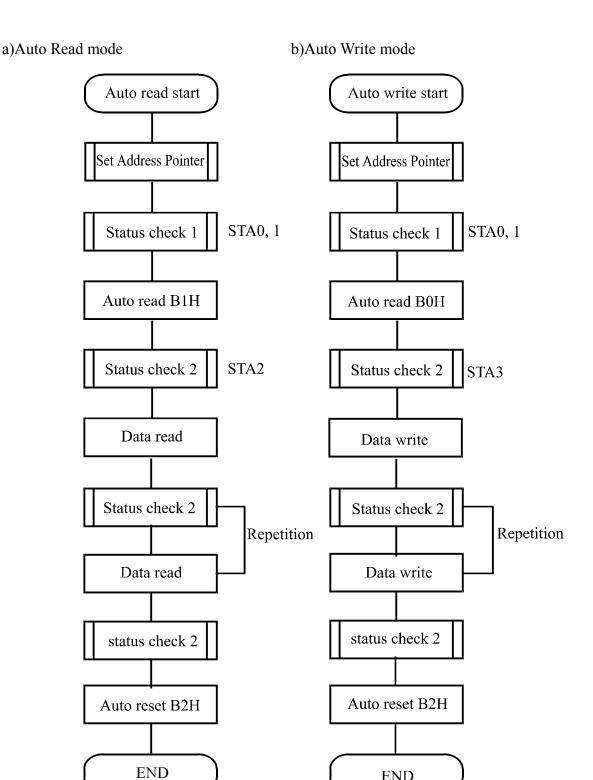
CODE	HEX.	FUNCTION	OPERAND
10110000	ВОН	Set Data Auto Write	_
1011001	B1H	Set Data Auto Read	_
10110010	В2Н	Auto Reset	_

The command is convenient for sending a full screen of data from the external display RAM. After setting Auto mode, a Data Write (or Read) command is need not be sent between each datum. A Data Auto Write (or Read) command must be sent after a Set Address Pointer command. After this command, the address pointer is automatically incremented by 1 after each datum. In Auto mode, the T6963C cannot accept any other commands.

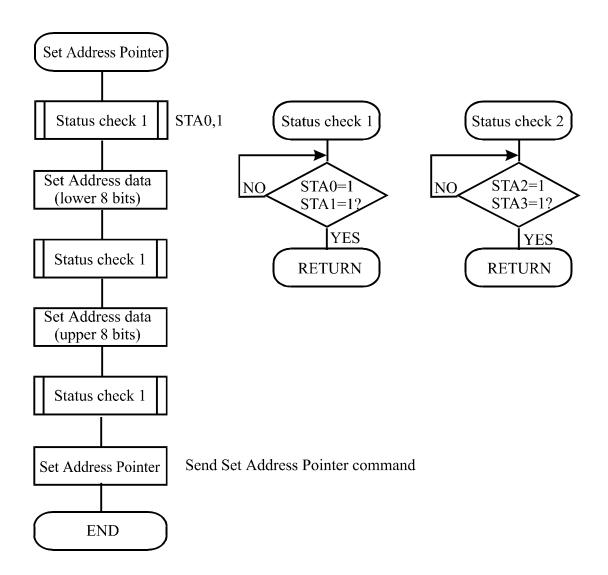
The Auto Reset command must be sent to the T69963C after all data has been sent, to clear Auto mode.

(Note) A Status check for Auto mode

(STA2, STA3 should be checked between sending of each datum. Auto Reset should be performed after checking STA3=1 (STA2=1.) Refer to the following flowchart.



**END** 

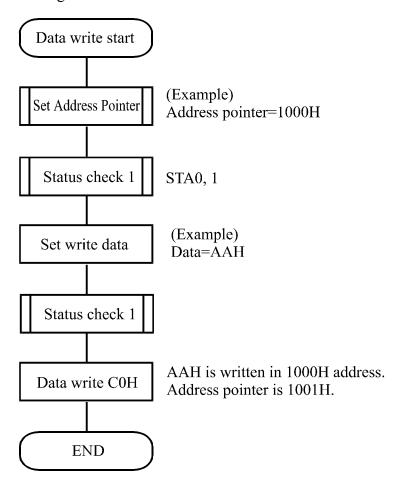


#### • Date Read/Write

CODE	HEX.	FUNCTION	OPERAND
11000000	С0Н	Data Write and Increment ADP	Data
11000001	С1Н	Data Read and Increment ADP	_
11000010	С2Н	Data Write and Decrement ADP	Data
11000011	СЗН	Data Read and Decrement ADP	_
11000100	С4Н	Data Write and Nonvariable ADP	Data
11000101	С5Н	Data Read and Nonvariable ADP	_

This command is used for writing data from the MPU to external display RAM, and reading data from external display RAM to the MPU. Data Write/Data Read should be executed after setting address using Set Address Pointer command. The address pointer can be automatically incremented or decremented using this command.

(Note)This command is necessary for each 1-byte datum.

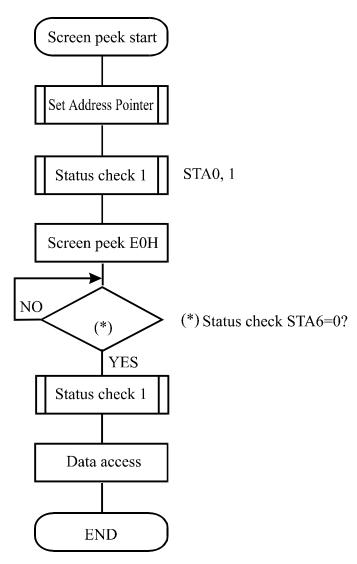


### Screen Peek

CODE	HEX.	FUNCTION	OPERAND
11100000	ЕОН	Screen Peek	—е

This command is used to transfer 1 byte of displayed data to the data stack; this byte can then be read from the MPU by data access. The logical combination of text and graphic display data on the LCD screen can be read by this command.

The status (STA6) should be checked just after the Screen Peek command. If the address determined by the Set Address Pointer command is not in the graphic area, this commands is ignored and a status flag (STA6) is set.



## • Screen Copy

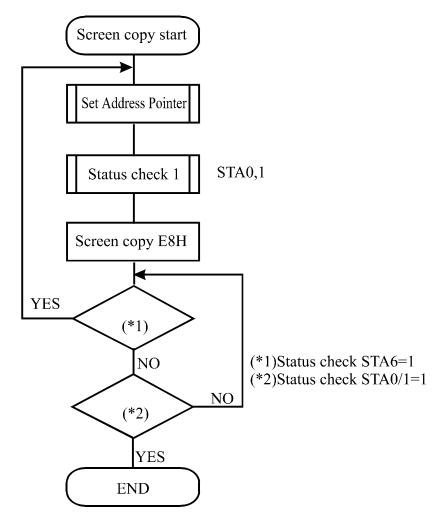
CODE	HEX.	FUNCTION	OPERAND
11101000	E8H	Screen Copy	_

This command copies a single raster line of data to the graphic area.

The start point must be set using the Set Address Pointer command.

(Note 1) If the attribute function is being used, this command is not available.

(With Attribute data is graphic area data.)



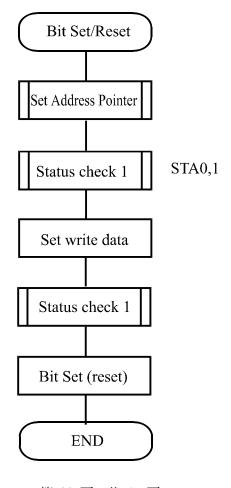
### • Bit Set/Reset

CODE	FUNCTION	OPERAND
11110xxx	Bit Reset	_
11111xxx	Bit Set	_
1111×000	Bit 0 (LSB)	_
1111×001	Bit 1	_
1111×010	Bit 2	_
1111×011	Bit 3	_
1111×100	Bit 4	_
1111×101	Bit 5	_
1111×110	Bit 6	
1111×111	Bit 7 (MSB)	_

X:invalid

This command use to set or reset a bit of the byte specified by the address pointer.

Only one bit can be set/reset at a time.



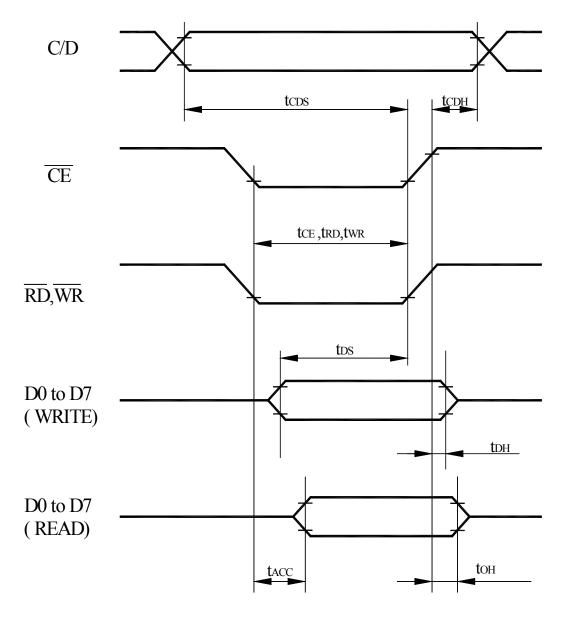
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# 10.Timing Characteristics

## **Bus Timing**

 $(V_{SS} = 0 V, VDD = 5 V)$ 

Item	Symbol	Min	Тур	Max	Unit
C/D Set-up Time	tcds	100	_	_	ns
C/D Hold Time	tсdн	10	_	_	ns
CE,RD,WR Pulse Width	tcds,trd,twr	80	_	_	ns
Data Set-up Time	tds	80	_	_	ns
Data Hold Time	tdн	40	_	_	ns
Access Time	tacc	_	_	150	ns
Output Hold Time	tон	10	_	50	ns



## 11.RELIABILITY

## Content of Reliability Test (wide temperature, -20°C ~70°C)

	Environmental Test		
<b>Test Item</b>	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long	80°C	2
righ Temperature storage	time.	200hrs	2
Low Temperature	Endurance test applying the high storage temperature for a long	-30°C	1,2
storage	time.	200hrs	1,2
High Temperature	Endurance test applying the electric stress (Voltage & Current) and	70℃	
Operation	the thermal stress to the element for a long time.	200hrs	
Low Temperature	Endurance test applying the electric stress under low temperature	-20°C	1
Operation	for a long time.	200hrs	1
High Tomporature/	The module should be allowed to stand at 60°C,90%RH max	60°C,90%RH	
High Temperature/ Humidity Operation	For 96hrs under no-load condition excluding the polarizer,	96hrs	1,2
riumanty Operation	Then taking it out and drying it at normal temperature.	Polits	
	The sample should be allowed stand the following 10 cycles of		
	operation		
Thermal shock resistance	-20°C 25°C 70°C	-20°C/70°C	
Thermal shock resistance		10 cycles	
	John James Dolling		
	1 cycle		
		Total fixed amplitude :	
		1.5mm	
	Endurance test applying the vibration during transportation and	Vibration Frequency:	
Vibration test	using.	10~55Hz	3
	using.	One cycle 60 seconds to 3	
		directions of X,Y,Z for	
		Each 15 minutes	
		VS=800V,RS=1.5kΩ	
Static electricity test	Endurance test applying the electric stress to the terminal.	CS=100pF	
•		1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

## 12.Backlight Information

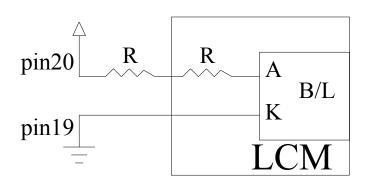
**Specification** 

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	57.6	64	100	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	v	
Reverse Voltage	VR	_	_	5	V	
Luminous Intensity	IV	200	250	_	CD/M2	ILED=64mA
LED Life Time (For Reference only)		_	50K	_	Hr.	ILED≦64mA 25°C,50-60%RH, (Note 1)
Color				White		,

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

## 2.Drive from pin19,pin20



# 13. Inspection specification

NO	Item		Criterion		AQL
01	Electrical Testing	1.1 Missing vertical, horized 1.2 Missing character, dot 1.3 Display malfunction. 1.4 No function or no display 1.5 Current consumption ed. 6 LCD viewing angle de 1.7 Mixed product types. 1.8 Contrast defect.	or icon.  lay.  xceeds product spec		0.65
02	Black or white spots on LCD (display only)	<ul><li>2.1 White and black spots three white or black sp</li><li>2.2 Densely spaced: No me</li></ul>	ots present.		2.5
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As follow $\Phi = (x + y)/2$ $X \qquad Y$ 3.2 Line type : (As following Length Leng	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	•	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size $\Phi$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

## O5 Scratches Follow NO.3 LCD black spots, white spots, contamination

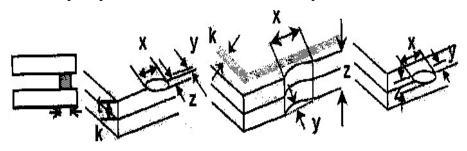
## Symbols Define:

x: Chip lengthy: Chip widthz: Chip thicknessk: Seal widtht: Glass thicknessa: LCD side length

L: Electrode pad length:

## 6.1 General glass chip:

6.1.1 Chip on panel surface and crack between panels:

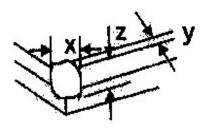


06 Chipped glass

z: Chip thickness y: Chip width x: Chip length  $Z \le 1/2t$  Not over viewing area  $x \le 1/8a$  2.5  $1/2t < z \le 2t$  Not exceed 1/3k  $x \le 1/8a$ 

⊙ If there are 2 or more chips, x is total length of each chip.

#### 6.1.2 Corner crack:



z: Chip thickness y: Chip width x: Chip length  $Z \le 1/2t$  Not over viewing area  $x \le 1/8a$   $1/2t < z \le 2t$  Not exceed 1/3k  $x \le 1/8a$ 

⊙ If there are 2 or more chips, x is the total length of each chip.

2.5

Symbols:

x: Chip length

y: Chip width

z: Chip thickness

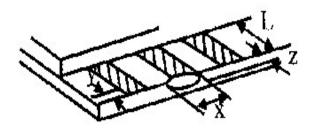
k: Seal width

t: Glass thickness a: LCD side length

L: Electrode pad length

6.2 Protrusion over terminal:

6.2.1 Chip on electrode pad:



y: Chip width

x: Chip length

z: Chip thickness

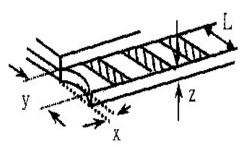
 $y \le 0.5 mm$ 

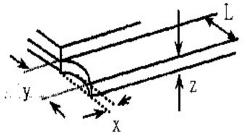
 $x \le 1/8a$ 

 $0 < z \le t$ 

6.2.2 Non-conductive portion:

Glass 06 crack





y: Chip width

 $y \leq L$ 

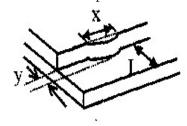
x: Chip length

 $x \le 1/8a$ 

z: Chip thickness

 $0 < z \le t$ 

- ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
- ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.
- 6.2.3 Substrate protuberance and internal crack.



y: width

x: length

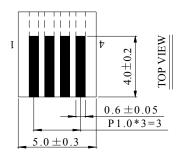
 $y \le 1/3L$ 

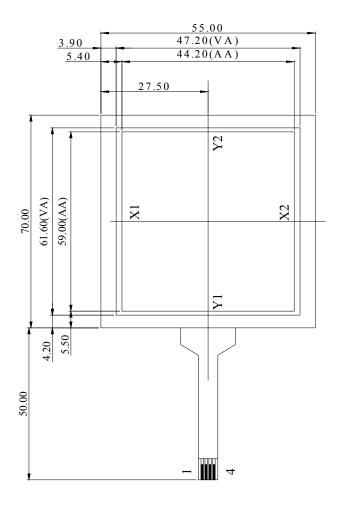
 $x \leq a$ 

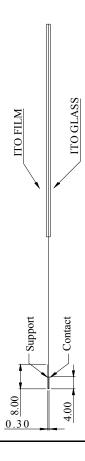
NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB、COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin	2.5
		must be present or look as if it cause the interface pin to sever.	
12	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12	appearance	component) is not burned into brown or black color.	
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	

# 14. Touch panel Information







## **ELECTRICAL SPECIFICATIONS**

ITEM	SPECIFICATION	CONDITION
ON RESISTANCE	200Ω ~ 900Ω	DIRECTION:X
	$200\Omega \sim 900\Omega$	DIRECTION:Y
INSULATION RESISTANCE	MORE THAN $20M\Omega$	DC 25V
CHATTERING TIME	LESS THAN 15 msec	100K PULL-UP
LINEARITY	±1.5%	X AXIS
	±1.5%	Y AXIS

## MACHINE SPECIFICATIONS

ITEM	SPECIFICATION	CONDITION
OPERATING FORCE	LESS THAN 80g	R8.0 HS 40 ° SILICON RUBBER OR R0.8 POLYACETAL PEN
SURFACE HARDNESS	MORE THAN 2H	PENCIL TEST
LIGHT TRANSMISSION	MORE THAN 80 %	@550nm HITACHI U3300
DURABILITY FOR PEN SELECTIONS	MORE THAN 1,200,000 TIMES	FORCE:250g SPEED:2cm/sec

## 15. Material List of Components for RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above lim	ited value is	set up acco	ording to Ro	HS.	•	

### 2. Process for RoHS requirement:

(1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp.:

Reflow:  $250\Box$ , 30 seconds Max.;

Connector soldering wave or hand soldering : 320 □, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.  $: 235\pm 5 \square$ ;

Recommended customer's soldering temp. of connector : 280 □, 3 seconds.

winstar <u>LCM Sam</u> Module Number :		ate Feedback Sheet Page: 1	
1 · Panel Specification :		- 1.6.1	
1. Panel Type:	Pass	□ NG ,	
2. View Direction:	Pass	□ NG ,	
3. Numbers of Dots:	☐ Pass	□ NG ,	
4. View Area:	Pass	□ NG ,	
5. Active Area:	Pass	□ NG ,	
6. Operating Temperature:	Pass	□ NG ,	
7. Storage Temperature:	☐ Pass	□ NG ,	
8. Others:			
2 · Mechanical Specification :			
1. PCB Size:	☐ Pass	□ NG ,	
2. Frame Size:	Pass	□ NG ,	
3. Materal of Frame:	☐ Pass	□ NG ,	
4. Connector Position:	☐ Pass	□ NG ,	
5. Fix Hole Position:	☐ Pass	□ NG ,	
6. Backlight Position:	☐ Pass	□ NG ,	
7. Thickness of PCB:	☐ Pass	□ NG ,	
8. Height of Frame to PCB:	☐ Pass	□ NG ,	
9. Height of Module:	☐ Pass	□ NG ,	
10. Others:	Pass	□ NG ,	
Relative Hole Size :			
1. Pitch of Connector:	Pass	□ NG ,	
2. Hole size of Connector:	Pass	□ NG ,	
3. Mounting Hole size:	☐ Pass	□ NG ,	
4. Mounting Hole Type:	☐ Pass	□ NG ,	
5. Others:	Pass	□ NG ,	
· Backlight Specification :			
1. B/L Type:	Pass	□ NG ,	
2. B/L Color:	Pass	□ NG ,	
3. B/L Driving Voltage (Refere	ence for LED	O Type):  Pass NG,	
4. B/L Driving Current:	Pass	□ NG ,	
5. Brightness of B/L:	Pass	□ NG ,	
6. B/L Solder Method:	Pass	□ NG ,	
7. Others:	Pass	□ NG ,	
7. Others:	_	□ NG , o page 2 <<	

lu	winstar ıle Number:		Page: 2
	<b>Electronic Characteristics o</b>		
1.	Input Voltage:	Pass	□ NG ,
2.	Supply Current:	Pass	□ NG ,
3.	Driving Voltage for LCD:	Pass	□ NG ,
4.	Contrast for LCD:	Pass	□ NG ,
5.	B/L Driving Method:	Pass	□ NG ,
6.	Negative Voltage Output:	Pass	□ NG ,
7.	Interface Function:	Pass	□ NG ,
8.	LCD Uniformity:	Pass	□ NG ,
9.	ESD test:	☐ Pass	□ NG ,
10.	Others:	☐ Pass	□ NG ,

**Date**: / /

Customer Signature : \_\_\_\_\_